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TITLE: MAP, LOW PROFILE, 21 X 21 PKG, 624 I/O, 0.8 MM PITCH	DOCUMENT NO: 98ASA00404D	REV: B
	STANDARD: NON-JEDEC	
	SOT1529-1	08 JAN 2016



NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
- 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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